

PATENT

As a below named inventor, I hereby declare that:

I believe I am the original, first, and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled "PROCESS FOR REDUCING IMPURITY LEVELS, STRESS, AND RESISTIVITY, AND INCREASING GRAIN SIZE OF COPPER FILLER IN TRENCHES AND VIAS OF INTEGRATED CIRCUIT STRUCTURES TO ENHANCE ELECTRICAL PERFORMANCE OF COPPER FILLER", the specification of which:

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)			Priority Claimed
(Number)	(Country)	(Date Filed)	Yes ___ No ___
			Yes ___ No ___

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a), regarding events which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.)	(Filing Date)	(Status)
(Application Serial No.)	(Filing Date)	(Status)

I hereby declare that all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint John P. Taylor, Reg. 22,369; Sandeep Jaggi, Reg. 43,331; Timothy R. Croll, Reg. 36,771; Leo J. Peters, Reg. 33,562; and Pete R. Scott, Reg. 33,279; as my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith and before competent international authorities.

Please send all correspondence to:

Sandeep Jaggi, Chief IP Counsel
LSI Logic Corporation
Legal Department - IP
1621 Barber Lane, MS D-106
Milpitas, CA 95035
(408) 954-4923

Wherefore I pray that Letters Patent be granted to me for the invention or discovery described and claimed in the foregoing specification and claims, and I hereby subscribe my name to the foregoing specification and claims, declaration, power of attorney, and this petition.

First Inventor's Full Name: Byung-Sung Kwak
(First) (Initial) (Last)

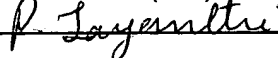
Inventor's Signature: 

Date: 9/23/03 Country of Citizenship: U.S.A

Residence Address: Portland, Oregon

Post Office Address: 5355 NW Paseo Terrace, Portland, OR 97229 USA

Second Inventor's Full Name: Jayanthi Pallinti
(First) (Initial) (Last)

Inventor's Signature: 

Date: 9/23/03 Country of Citizenship: India

Residence Address: Gresham, Oregon

Post Office Address: 1718 SE Orient Drive #3117, Gresham, OR 97080 USA

Third Inventor's Full Name: William Barth
(First) (Initial) (Last)

Inventor's Signature: 

Date: 9/23/03 Country of Citizenship: U.S.A.

Residence Address: Gresham, Oregon

Post Office Address: 1642 SW Nancy Drive, Gresham, OR 97080

Fourth Inventor's Full Name: _____
(First) (Initial) (Last)

Inventor's Signature: _____

Date: _____ Country of Citizenship: _____

Residence Address: _____

Post Office Address: _____